

GLOSSARY OF TECHNICAL TERMS

This glossary contains explanations of certain technical terms used in this document in connection with our Company and its business. Such terminology and meanings may not correspond to standard industry meanings or usages of those terms.

This glossary of technical terms contains terms used in this document as they relate to our business. As such, these terms and their meanings may not always correspond to standard industry meaning or usage of these terms.

“ADAS”	advanced driver assistance systems
“ADCU”	automated driving control units
“AI”	artificial intelligence
“AIoT”	artificial intelligence of things
“AI servers”	servers specifically built to handle the demands of AI workloads
“AR”	augmented reality
“ASIC”	application-specific integrated circuit
“aspect ratio”	the ratio of the board thickness to the drill hole diameter for plated-through holes, or the ratio of the hole depth to the drill hole diameter for blind holes
“back-drilling”	a drilling process that removes part of the copper layer from the hole wall on the plated-through hole surface
“blind via”	a type of vias extending only to one surface of PCB
“buried via”	a type of vias not extending to the surface of PCB
“BGA”	ball grid array
“BI”	business intelligence
“BMS”	battery management system
“CAM”	computer-aided manufacturing
“CMA”	China metrology accreditation
“CPU”	central processing unit
“digital twin”	a virtual model constructed for a physical entity or system, which can simulate the operating status of the physical entity or system in real time, thereby enabling dynamic monitoring and optimization control of its operation process

GLOSSARY OF TECHNICAL TERMS

“EAP”	equipment automation program
“EMS”	electronics manufacturing services
“ERP”	enterprise resource planning
“ESG”	environmental, social and governance
“EV”	electric vehicle
“fifth/sixth/seventh-generation millimeter-wave radar boards”	PCB used in the fifth/sixth/seventh-generation millimeter-wave radar. The fifth-generation millimeter-wave radar represents a breakthrough from its predecessors, adding vertical height perception capabilities to the three-dimensional perception of speed and horizontal angle, making it a four-dimensional millimeter-wave radar equipped with four-dimensional perception. The sixth-generation millimeter-wave radar upgrades perception capabilities such as detection range and horizontal angle resolution. The seventh-generation millimeter-wave radar further enhances the above perception performance, better meeting the perception requirements of advanced intelligent driving functions
“FPGA”	field programmable gate array
“FPC”	flexible printed circuit(s)
“FR4”	flame retardant 4, the industry-standard flame-retardant grade of composite materials used for PCB
“GLA”	gross land area
“GPS”	global positioning system
“GPU”	graphics processing unit
“HDI”	high-density interconnect
“high-build-up”	manufacturing process involving three or more laser drilling and lamination processes
“HLC”	high layer count
“IASB”	International Accounting Standards Board
“IPD”	integrated product development
“LDI”	laser direct imaging
“LED”	light emitting diode

GLOSSARY OF TECHNICAL TERMS

“LiDAR”	light detection and ranging
“MES”	manufacturing execution system
“mil”	a length unit equal to one-thousandth of an inch
“MLPCB”	multi-layer PCB
“MPCB”	metal-based PCB
“MRP”	material requirements planning
“mSAP”	modified semi-additive process
“M7-to-M9”	the grading of copper-clad laminates. The higher grade represents lower signal transmission losses and better high-speed transmission performance
“OLED”	organic light-emitting diode
“PCB”	printed circuit board(s)
“PPO”	polyphenylene oxide
“prepreg”	also known as “PP sheet” or “resin sheet”, a sheet or roll material made from fiber-reinforced material impregnated with thermosetting resin and cured to the B-stage (semi-cured)
“PTFE”	polytetrafluoroethylene, a polymeric material synthesized through polymerization of tetrafluoroethylene as the monomer
“rigid-flex PCB”	a hybrid type of printed circuit board that combined elements of both RPCB and FPC into a single unit
“RPA”	robotic process automation
“R&D”	research and development
“RPCB”	rigid PCB
“SBTi”	science based targets initiative
“signal integrity”	the quality of the signal along the transmission path
“SLP”	substrate-like PCB
“SMT”	surface mount technology

GLOSSARY OF TECHNICAL TERMS

“sq.m.”	square meter(s)
“SRM”	supplier relationship management
“stub”	the residual conductive part in a via
“Tier 1 automotive suppliers”	suppliers that supply parts or systems directly to automotive original equipment manufacturers
“TOC”	theory of constraints
“vias”	holes that are drilled through the board to create pathways for electrical connections between different layers
“VR”	virtual reality